

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHENCHI LUO	02/08/2018
HYEJUNG KIM	02/08/2018
SEOK-JUN LEE	02/08/2018
DAVID LIU	02/08/2018
MICHAEL POLLEY	02/08/2018
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD.
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	16677
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15892195
CORRESPONDENCE DATA	
Fax Number:	(972)628-3616
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	9726283600
Email:	patents@munckwilson.com
Correspondent Name:	DOCKET CLERK - SAMS
Address Line 1:	P.O. DRAWER 800889
Address Line 4:	DALLAS, TEXAS 75380
ATTORNEY DOCKET NUMBER:	2017.06.003.MP0
NAME OF SUBMITTER:	MICHAEL G. RODRIGUEZ
SIGNATURE:	/Michael G. Rodriguez/
DATE SIGNED:	05/08/2018
Total Attachments: 5	
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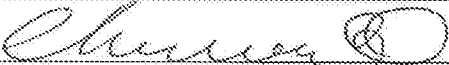
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DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET
(37 CFR 1.76) AND ASSIGNMENT

Title of Invention	DYNAMIC MEMORY MAPPING FOR NEURAL NETWORKS
As the below named inventor, I hereby declare that:	
This combined declaration and assignment is directed to: <input checked="" type="checkbox"/> The attached application, or <input type="checkbox"/> United States application or PCT International application number _____ filed on _____	
The above-identified application was made or authorized to be made by me.	
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.	
I have reviewed and understand the contents of the application including the claims, for which this combined declaration and assignment is being submitted.	
I am aware of the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR 1.56.	
WHEREAS, <u>Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 129, Samsung-ro, Yeongtong-gu Suwon-si, Gyeonggi-do, Korea</u> (hereinafter referred to as "ASSIGNEE"), desires to acquire the entire right, title and interest in said invention and to any patent that may be granted thereon in the United States and foreign countries;	
NOW, THEREFORE, for good and valuable consideration, the receipt whereof is hereby acknowledged, I, hereby sell, assign and transfer to said ASSIGNEE, its successors and assigns, the entire right, title and interest in the above-identified application and the invention disclosed therein in all countries, including all divisional applications, continuation applications, and corresponding priority applications including those to which priority is claimed under the International Convention of Paris including under 35 U.S.C. 119, substitutions, and renewals thereof, and to all patents that may be granted thereon, and all reissues thereof.	
I hereby authorize and request the Patent Office Officials in the United States and all foreign countries to issue patents, when granted, to said ASSIGNEE, its successors and assigns. Further, I agree that said ASSIGNEE, its successors and assigns, may apply for patents for the invention in foreign countries without further authorization from me. Also, I agree to execute all papers and generally to do everything possible to aid said ASSIGNEE, its successors and assigns, in obtaining and enforcing patents for the invention in all countries.	
I hereby acknowledge that any willful false statement made in this combined declaration and assignment is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.	
LEGAL NAME OF SOLE INVENTOR (e.g., full first name, middle initial, last name)	
Inventor: <u>Chenchi Luo</u> Date: <u>02/08/2018</u>	
Signature: <u></u>	

LEGAL NAME OF SECOND INVENTOR (e.g., full first name, middle initial, last name)

Inventor: Hyejung Kim

Date: 02/08/2012


Signature: _____



LEGAL NAME OF THIRD INVENTOR (e.g., full first name, middle initial, last name)

Inventor: Seok-Jun Lee

Date: Feb. 8th. 2018

Signature: 

LEGAL NAME OF FOURTH INVENTOR (e.g., full first name, middle initial, last name)

Inventor: David Liu

Date:

2/2/18

Signature:



LEGAL NAME OF FOURTH INVENTOR (e.g., full first name, middle initial, last name)

Inventor: Michael Polley

Date:

2/8/18

Signature:

Michael Polley